

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No.: 09/114,665
Filing Date: July 13, 1998
Applicant: Thomas R. Bieler, et al.
Group Art Unit: 1742
Examiner: I.P. Sikyin
Title: METHODS FOR PRODUCING LEAD-FREE IN-SITU COMPOSITE SOLDER ALLOYS
Attorney Docket: 6550-000013

Commissioner of Patents and Trademarks
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.111

Dear Sir:

In response to the Office Action mailed July 16, 2001, please enter the following amendments and consider the accompanying remarks.

IN THE CLAIMS

Please cancel Claims 1-11, and 13-25, without prejudice. Please add the following new claims 26-58.

26. (new) A method for producing an *in-situ* composite solder having an intermetallic component, comprising the steps of:

(a) providing a matrix solder comprising two or more metals;

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